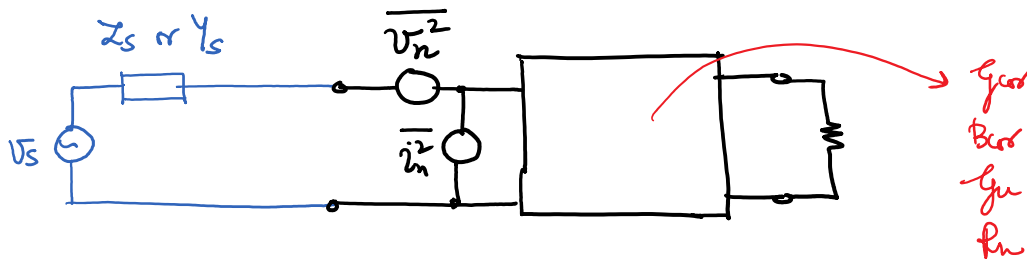


# EE 513 - Lecture 13

Tuesday, October 2, 2018 9:34 AM

$$Y_s = \frac{1}{Z_s}$$



Noise Admittance formalism:

$$Y_{s,opt} = G_{s,opt} + jB_{s,opt} \rightarrow B_{s,opt} = -B_{oor}$$

$$G_{s,opt} = \sqrt{g_{oor}^2 + \frac{g_u}{R_n}}$$

$$R_n \triangleq \frac{\overline{v_n^2}}{4kT\Delta f}$$

$$g_u \triangleq \frac{\overline{i_n^2}}{4kT\Delta f}$$

$$F_{min} = 1 + 2R_n(g_{oor} + G_{s,opt})$$

$$F = F_{min} + \frac{R_n}{g_s} |Y_s - Y_{s,opt}|^2$$

$$Y_s = Y_{s,opt} \Rightarrow F = F_{min}$$

$R_n \Rightarrow$  Sensitivity parameter of NF to noise impedance mismatch

# Noise Impedance formalism:

$$i_n = \hat{i}_n$$

$$v_n = v_u + v_c = v_u + Z_{cr}' i_n$$

$$Z_{cr}' = R_{cr}' + jX_{cr}'$$

$$Z_{cr}' \neq Y_{cr}$$

$$Z_s = Z_{s,opt} \text{ for } F = f_{min}$$

$$R_{s,opt} + jX_{s,opt}$$

$$X_{s,opt} = -X_{cr}'$$

$$\sqrt{R_{cr}'^2 + \frac{R_u}{G_n'}}$$

$$f_{min} = 1 + 2G_n' (R_{cr}' + R_{s,opt})$$

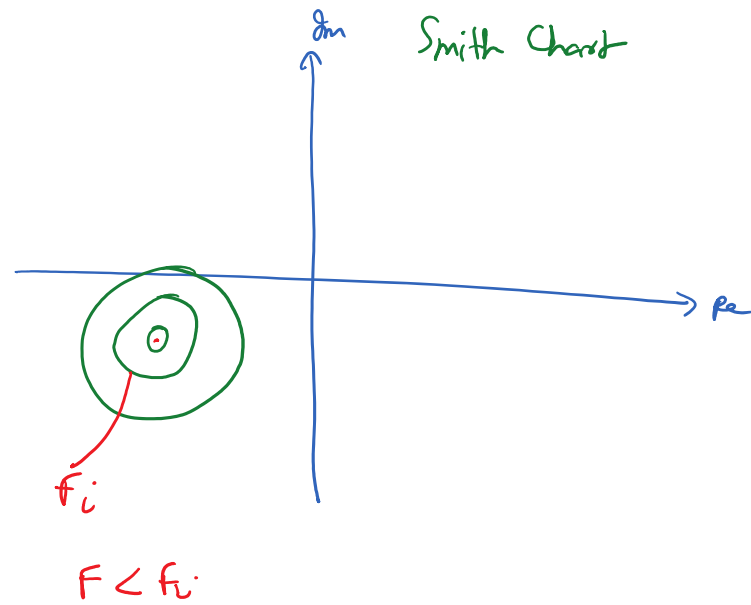
$$4 \quad F = f_{min} + \frac{G_n'}{R_s} |Z_s - Z_{s,opt}|^2$$

$$G_n' \triangleq \frac{\overline{i_n^2}}{4kT\Delta f}$$

$$R_u' \triangleq \frac{\overline{v_u^2}}{4kT\Delta f}$$

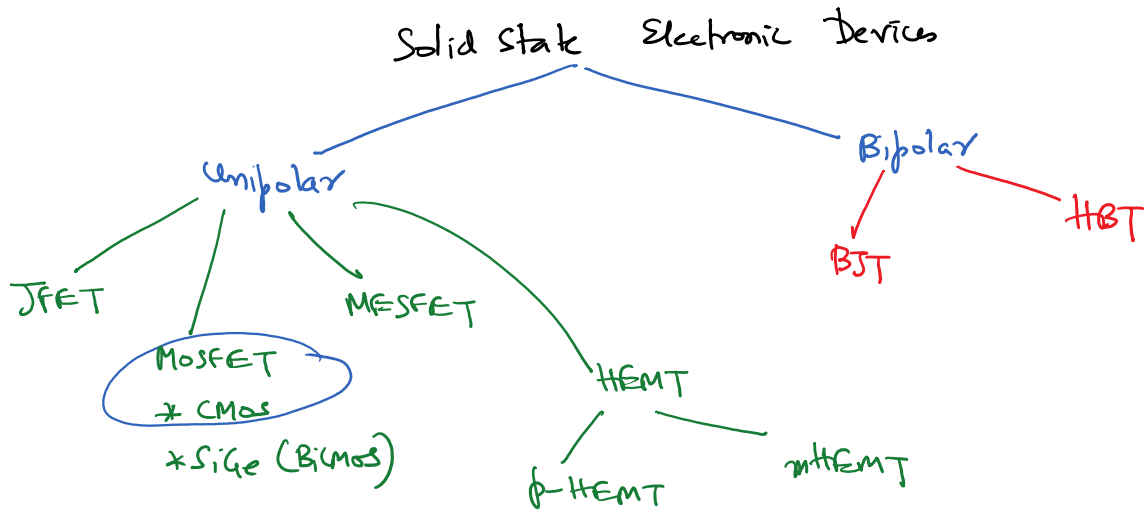
## Constant Noise Circles

$$F = F_{\min} + \frac{R_n}{g_s} |Y_s - Y_{s, \text{opt}}|^2$$



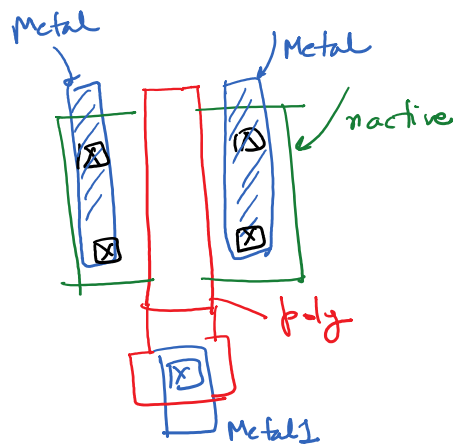
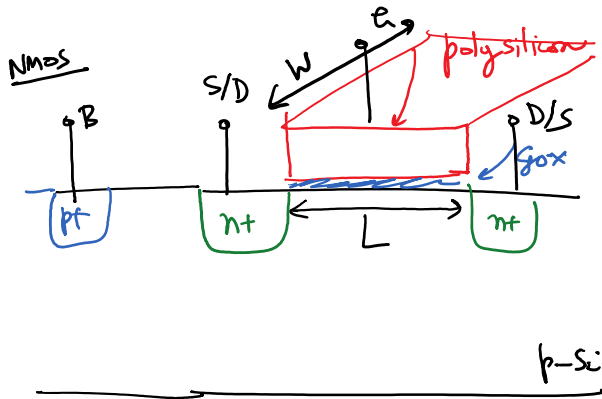
## Chapter-4

Tuesday, October 2, 2018 9:50 AM



Si  
SiGe  
GaAs  
GaN

MOSFETs (CMOS)  $\begin{cases} \text{NMOS} \\ \text{PMOS} \end{cases}$



Long-channel  $L > 1\mu m$

○  $V_{GS} < V_{THN}$  Cutoff

$V_{GS} > V_{THN}$

$V_{DS} < V_{GS} - V_{THN}$   
(Triode)

$V_{DS} > V_{GS} - V_{THN}$   
 $V_{DS,sat}$   
(SAT)

$$I_D = \begin{cases} K_n \frac{W}{L} \left[ (V_{GS} - V_{THN}) V_{DS} - \frac{V_{DS}^2}{2} \right] \\ \frac{1}{2} K_n \frac{W}{L} (V_{GS} - V_{THN})^2 \\ \times (1 + \lambda V_{DS}) \end{cases}$$

# Nanoscale MOSFET (before FINFETs)

Silicide  $\Rightarrow$  Co or Ti reacting with Si  
 $\rightarrow$  silicide

$V_{DD}$  has been shrinking

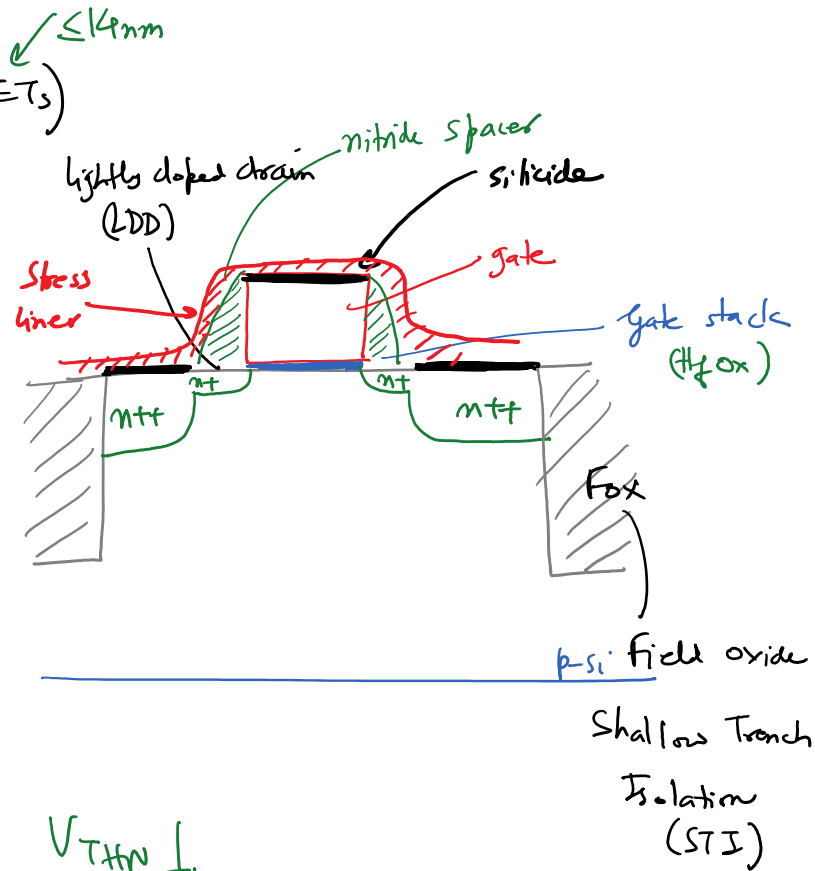
0.5  $\mu$ m CMOS  $\rightarrow$  5V

6  $\mu$ m CMOS  $\rightarrow$  1V

14nm CMOS  $\Rightarrow$  0.8-1V

$V_{THN} \downarrow$

Metal gates for controlling the work function  $\rightarrow V_{THN}$ .



## DC I-V characteristics

\* Short-channel I-V characteristics depart from the square-law equations

In simplest form:-

In saturation

$$I_D = W \mu_{\text{eff}} C_{\text{ox}}^{\text{inv}} (V_{\text{GS}} - V_{\text{THN}}) (1 + \lambda V_{\text{DS}})$$

$\mu_{\text{eff}} \Rightarrow$  effective carrier velocity at the source

$C_{\text{ox}}^{\text{inv}} \Rightarrow$  effective capacitance of the channel in inversion

$\lambda \Rightarrow$  channel length parameter

\* mobility  $\mu_n \Rightarrow$  has been replaced by  $v_{\text{sat}}$  (velocity saturation regime)

\* not a square law equation anymore

DIBL  $\Rightarrow$  Drain induced barrier lowering

$$V_{\text{DS}} \uparrow \Rightarrow V_{\text{THN}} \downarrow$$

$V_{\text{THN}}$  has dependence upon length

$$L \uparrow \Rightarrow V_{\text{THN}} \uparrow$$

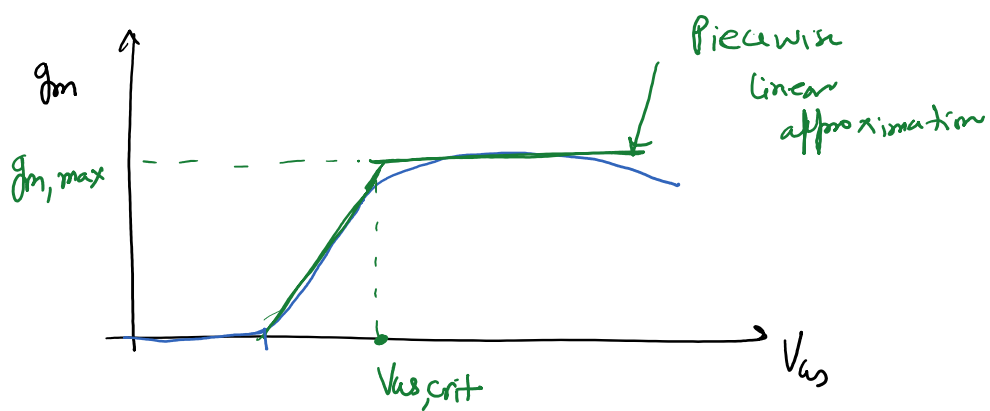
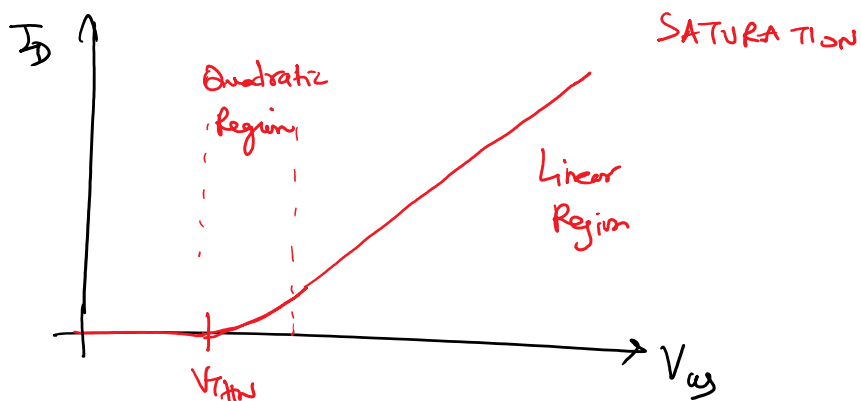
\* Can't fix a  $V_{\text{DS}}$  and "Size" all transistors accordingly

$\hookrightarrow$  Constant Current Density Design Techniques

$$\hookrightarrow \frac{I_D}{W}$$

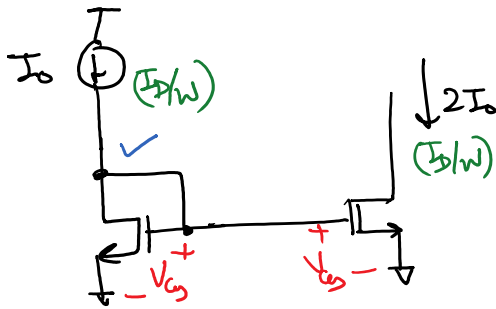
Fig 4.35

$$g_m = \frac{\partial I_D}{\partial V_{GS}}$$





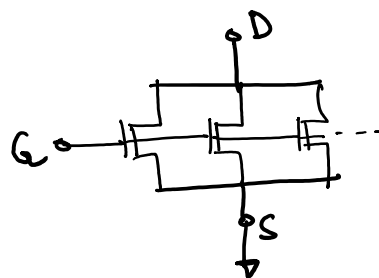
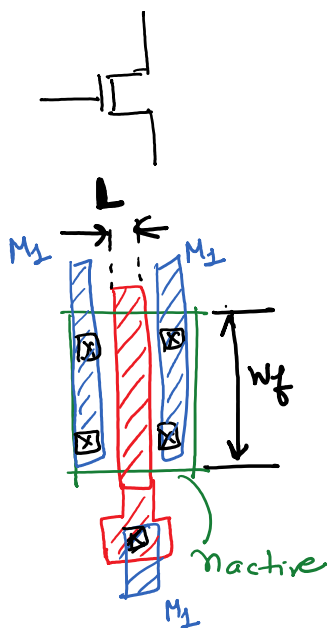
## Constant Current Density ( $I_D/w$ ) Design Methodology



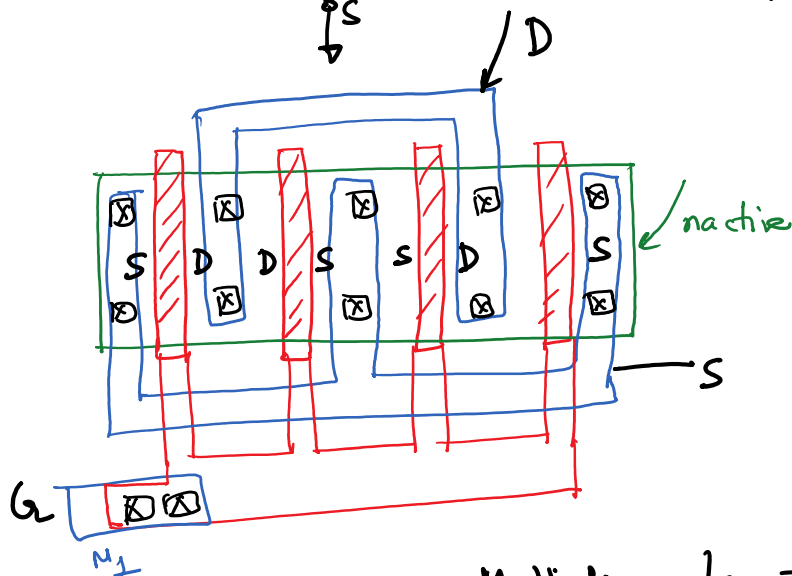
- ① fix the gate length ( $L \geq 2-5 \mu\text{m}$  typically)
  - ② Transistors are first biased at the desired constant current density ( $I_D/w$ )
  - ② Then the desired current ( $I_D$ ) or  $g_m$  are achieved by fixing the gate finger width ( $W_f$ ) and varying the number of fingers in parallel
- Essentially we are keeping  $\frac{I_D}{w}$  constant across the circuit

$$\frac{I_D}{w} = \text{constant} \Rightarrow \frac{g_m}{I_D} = \text{constant}$$

\* Actual value of  $V_{GS}$  is of secondary importance.



Source has more capacitance  
↳ connected to ground

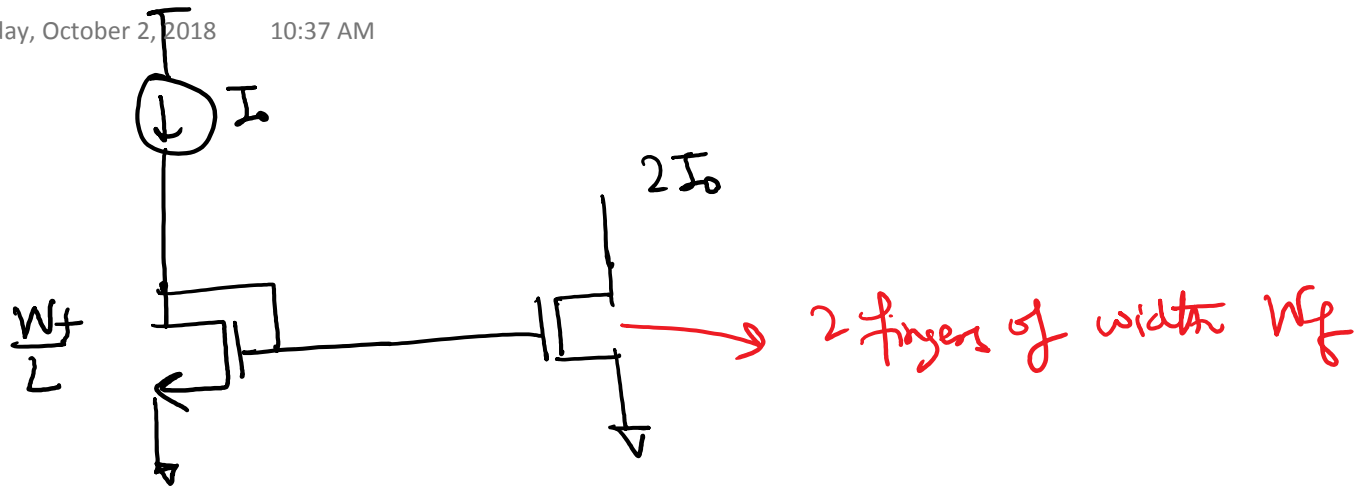


Multi-finger layout

$N_f = \text{Number of fingers} = 4 \text{ here}$

$$\text{Effective } W = N_f \cdot w_f$$

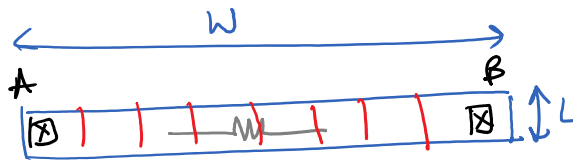
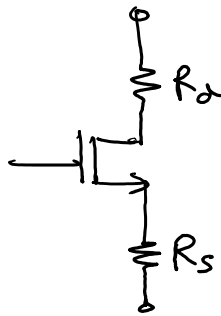
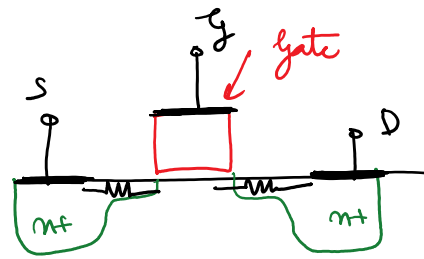
\* FinFETs designs are more restrictive



Layout Matching Techniques-

# Parasitic Resistances and Capacitances :

\* Source and drain resistances due to the LDD

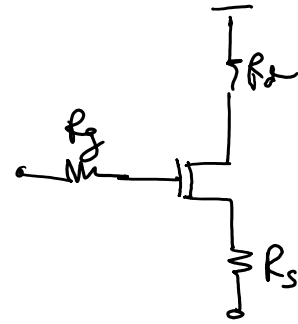
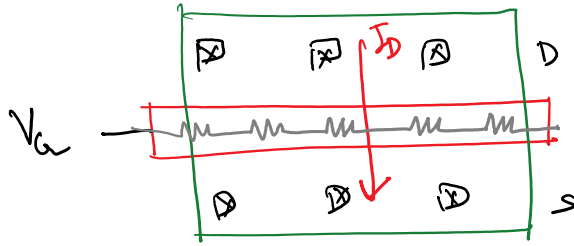


Resistance per square  $\Rightarrow R_{\square}$

$$R_{AB} = R_{\square} \times \text{num of squares}$$

Different material on chip have different  $R_{\square}$

$$R = R_{\square} \cdot \frac{W}{L}$$



Effectively Gate Resistance

$$R_g \approx \frac{1}{3} R_{\square} \frac{W}{L}$$

due to distributed nature

\* See Section 4.2.5 in the Book